



Material Content Data Sheet



Sales Product Name		BTT6200-4EMA		Issued		20. May 2015		
MA#		MA001369088						
Package		PG-SSOP-24-14		Weight*		151.85 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.840	1.87	1.87	18701	18701
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		112	
	non noble metal	zinc	7440-66-6	0.068	0.04		446	
	non noble metal	iron	7439-89-6	1.355	0.89		8920	
wire	non noble metal	copper	7440-50-8	54.998	36.22	37.16	362182	371660
	non noble metal	copper	7440-50-8	0.627	0.41	0.41	4131	4131
	organic material	carbon black	1333-86-4	0.173	0.11		1142	
encapsulation	plastics	epoxy resin	-	7.976	5.25		52524	
	inorganic material	silicondioxide	60676-86-0	78.546	51.74	57.10	517248	570914
leadfinish	non noble metal	tin	7440-31-5	2.947	1.94	1.94	19409	19409
plating	noble metal	silver	7440-22-4	1.379	0.91	0.91	9082	9082
glue	plastics	epoxy resin	-	0.162	0.11		1068	
	noble metal	silver	7440-22-4	0.765	0.50	0.61	5035	6103
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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